

Glass processing services

EXCEPTIONAL EXPERTISE IN GLASS

Ultra-high precision & quality

With glass being a demanding material, we offer more than 10 years of experience in glass processing, including drilling, cutting and dicing.



Ultra-high
precision results



Small feature
sizes



Irregular shape
holes

Typical features

- A variety of glass types and major suppliers - Corning, Schott, Hoya, AGC
- Wafer size up to 200 mm x 200 mm (8")
- Wafer thickness from 30 μm to 10 mm
- Circular, square and other-shaped holes
- Straight hole cross section | no taper
- Low chipping <10 μm
- Smooth side walls, Ra <1 μm
- Typical min. hole size 20 μm (round)
- Positional accuracy $\pm 3 \mu\text{m}$
- No debris on back and front surfaces
- No sagging around holes
- Aspect ratio up to 1:100
- High throughput and yield
- Ability to work with metalized glass types (e.g. Au, Pt, Ni, Cr, Mo)
- Minimal or no post-processing is needed

Get in touch

www.wophotonics.com

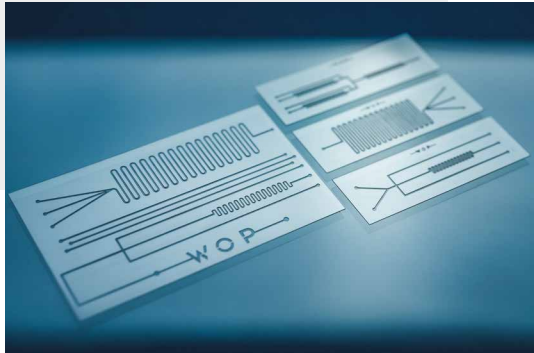
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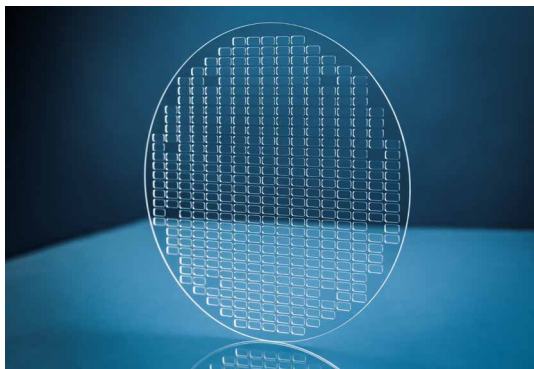


Applications

- Sensors (image, pressure, gal acceleration and other)
- Advanced packaging applications
- Semiconductors and other functional devices
- MEMS
- Wafer-level optics
- Gyroscopes
- Aerospace applications
- Analytical chips



Microfluidic Chips & Devices

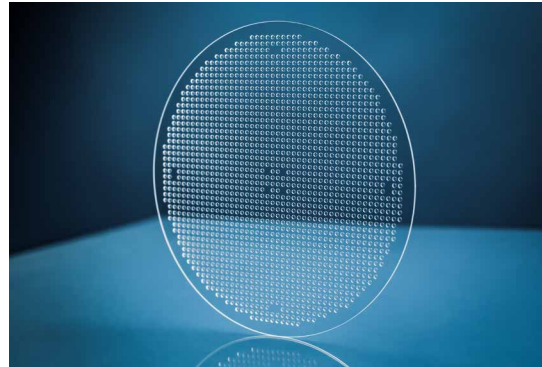


Packaging Glass Products



Glass Cutting

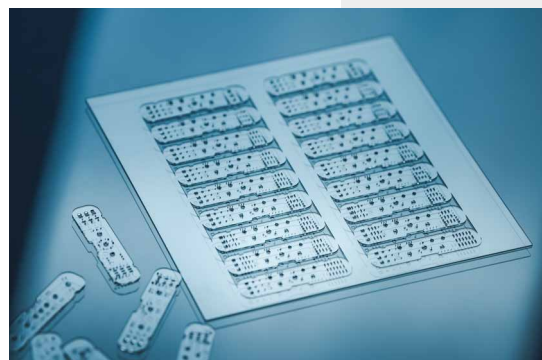
Assortment



Micro Drilled Glass | Glass Spacers



Glass Carrier Wafers



Glass Guide Plates for Probe Cards

